

SN74ACT32 Quadruple 2-Input Positive-or Gates

1 Features

- 4.5V to 5.5V V_{CC} operation
- Inputs accept voltages to 5.5V
- Max t_{pd} of 10ns at 5V
- Inputs are TTL-voltage compatible

2 Description

The 'ACT32 devices are quadruple 2-input positive-OR gates. The devices perform the Boolean function $Y = A + B$ or $Y = \bar{A} \cdot \bar{B}$ in positive logic.

Device Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾	BODY SIZE ⁽³⁾
SN74ACT32	PW (TSSOP, 14)	5mm × 6.4mm	5mm × 4.40mm
	D (SOIC, 14)	8.65mm × 6mm	8.65mm × 3.9mm
	DB (SSOP, 14)	6.2mm × 7.8mm	6.2mm × 5.3mm
	N (PDIP, 14)	19.3mm × 9.4mm	19.3mm × 6.35mm
	NS (SOP, 14)	10.2mm × 7.8mm	10.3mm × 5.3mm

- (1) For more information, see [Section 10](#).
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.
- (3) The body size (length × width) is a nominal value and does not include pins.



Logic Diagram, Each Gate (Positive Logic)



Table of Contents

1 Features	1	7 Application and Implementation	8
2 Description	1	7.1 Power Supply Recommendations.....	8
3 Pin Configuration and Functions	3	7.2 Layout.....	8
4 Specifications	4	8 Device and Documentation Support	8
4.1 Absolute Maximum Ratings.....	4	8.1 Documentation Support (Analog).....	9
4.2 Recommended Operating Conditions.....	4	8.2 Receiving Notification of Documentation Updates.....	9
4.3 Thermal Information.....	5	8.3 Support Resources.....	9
4.4 Electrical Characteristics.....	5	8.4 Trademarks.....	9
4.5 Switching Characteristics.....	5	8.5 Electrostatic Discharge Caution.....	9
4.6 Operating Characteristics.....	5	8.6 Glossary.....	9
5 Parameter Measurement Information	6	9 Revision History	9
6 Detailed Description	7	10 Mechanical, Packaging, and Orderable Information	9
6.1 Functional Block Diagram.....	7		
6.2 Device Functional Modes.....	7		

3 Pin Configuration and Functions

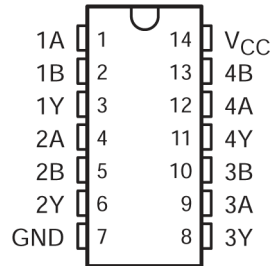


Figure 3-1. SN74ACT32 D, DB, N, NS, or PW Package (Top View)

Table 3-1. Pin Functions

NAME	PIN		TYPE ⁽¹⁾	DESCRIPTION
	SN74ACT32			
	D, DB, DGV, N, NS, PW, RGY, BQA			
1A	1		I	1A Input
1B	2		I	1B Input
1Y	3		O	1Y Output
2A	4		I	2A Input
2B	5		I	2B Input
2Y	6		O	2Y Output
3A	9		I	3A Input
3B	10		I	3B Input
3Y	8		O	3Y Output
4A	12		I	4A Input
4B	13		I	4B Input
4Y	11		O	4Y Output
GND	7		—	Ground Pin
NC	—		—	No Connection
V _{CC}	14		—	Power Pin

(1) Signal Types: I = Input, O = Output, I/O = Input or Output.

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	-0.5	7	V
V _I ⁽²⁾	Input voltage range	-0.5	V _{CC} + 0.5	V
V _O ⁽²⁾	Output voltage range	-0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	(V _I < 0 or V _I > V _{CC})		±20 mA
I _{OK}	Output clamp current	(V _O < 0 or V _O > V _{CC})		±20 mA
I _O	Continuous output current	(V _O = 0 or V _{CC})		±50 mA
	Continuous current through V _{CC} or GND			±200 mA
T _{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

4.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		SN74ACT32		UNIT
		MIN	MAX	
V _{CC}	Supply voltage	4.5	5.5	V
V _{IH}	High-level input voltage	2		V
V _{IL}	Low-level input voltage		0.8	V
V _I	Input voltage	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current		-24	mA
I _{OL}	Low-level output current		24	mA
Δt/Δv	Input transition rise or fall rate		8	ns/V
T _A	Operating free-air temperature	-40	85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

4.3 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74ACT32					UNIT
		D (SOIC)	DB (SSOP)	N (PDIP)	NS (SOP)	PW (TSSOP)	
		14	14	14	14	14	
R _{θJA}	Junction-to-ambient thermal resistance	119.9	96	80	76	145.7	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

4.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN74ACT32		UNIT
			MIN	TYP	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	4.5 V	4.4			4.4		V
		5.5 V	5.4			5.4		
	I _{OH} = -24 mA	4.5 V	3.86			3.76		
		5.5 V	4.86			4.76		
	I _{OH} = -50 mA ⁽¹⁾	5.5 V						
I _{OH} = -75 mA ⁽¹⁾	5.5 V				3.85			
V _{OL}	I _{OL} = 50 μA	4.5 V	0.001		0.1	0.1		V
		5.5 V	0.001		0.1	0.1		
	I _{OL} = 24 mA	5.5 V			0.36	0.44		
		5.5 V			0.36	0.44		
	I _{OL} = 50 mA ⁽¹⁾	5.5 V						
I _{OL} = 75 mA ⁽¹⁾	5.5 V				1.65			
I _I	V _I = V _{CC} or GND	5.5 V			±0.1	±1		μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			2	20		μA
ΔI _{CC} ⁽²⁾	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.6	1.5		mA
C _i	V _I = V _{CC} or GND	5 V			2.6			pF

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 2 ms.
(2) This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

4.5 Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

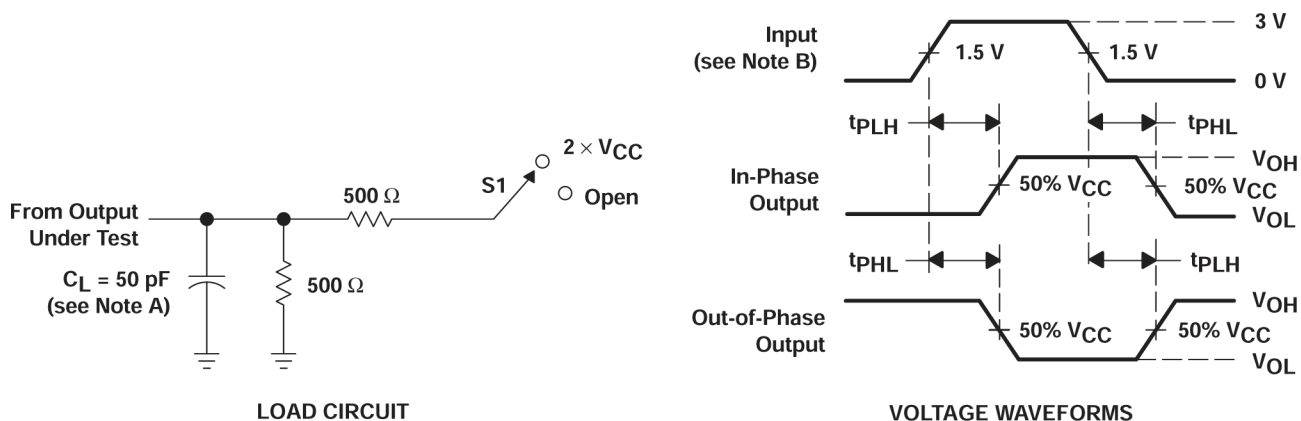
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			SN74ACT32		UNIT
			MIN	TYP	MAX	MIN	MAX	
t _{PLH}	A or B	Y	1	6.5	9	1	10	ns
t _{PHL}			1	6.5	9	1	10	

4.6 Operating Characteristics

V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	C _L = 50 pF, f = 1 MHz	40	pF

5 Parameter Measurement Information



- A. C_L includes probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 5-1. Load Circuit and Voltage Waveforms

TEST	S1
t_{PLH}/t_{PHL}	Open

6 Detailed Description

6.1 Functional Block Diagram



Figure 6-1. Logic Diagram, Each Gate (Positive Logic)

6.2 Device Functional Modes

Table 6-1. Function Table
(Each Gate)

INPUTS		OUTPUT
A	B	Y
H	X	H
X	H	H
L	L	L

7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- μF capacitor is recommended for this device. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. The 0.1- μF and 1- μF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results, as shown in *Layout Example*.

7.2 Layout

7.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

7.2.2 Layout Example

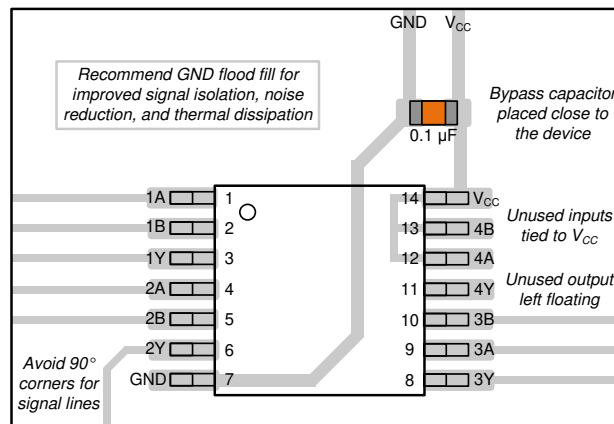


Figure 7-1. Example layout for the SN74ACT32

8 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

8.1 Documentation Support (Analog)

8.1.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN74ACT32	Click here	Click here	Click here	Click here	Click here

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](#). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
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8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision C (October 2003) to Revision D (July 2024)	Page
• Added <i>Device Information</i> table, <i>Pin Functions</i> table, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , Application and Implementation section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section	1
• Updated RθJA values: D = 86 to 119.9, PW = 113 to 145.7, all values in °C/W.....	5

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ACT32D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 85	ACT32	
SN74ACT32DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD32	Samples
SN74ACT32DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT32	Samples
SN74ACT32N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74ACT32N	Samples
SN74ACT32NSR	ACTIVE	SOP	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ACT32	Samples
SN74ACT32PW	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 85	AD32	
SN74ACT32PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD32	Samples
SN74ACT32PWRG4	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AD32	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT32DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74ACT32DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT32DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ACT32NSR	SOP	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74ACT32PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74ACT32PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74ACT32PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74ACT32PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT32DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74ACT32DR	SOIC	D	14	2500	353.0	353.0	32.0
SN74ACT32DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74ACT32NSR	SOP	NS	14	2000	356.0	356.0	35.0
SN74ACT32PWR	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74ACT32PWR	TSSOP	PW	14	2000	353.0	353.0	32.0
SN74ACT32PWRG4	TSSOP	PW	14	2000	356.0	356.0	35.0
SN74ACT32PWRG4	TSSOP	PW	14	2000	353.0	353.0	32.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ACT32N	N	PDIP	14	25	506	13.97	11230	4.32
SN74ACT32N	N	PDIP	14	25	506	13.97	11230	4.32

D0014A



PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4220718/A 09/2016

NOTES:

- All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm, per side.
- Reference JEDEC registration MS-012, variation AB.

EXAMPLE BOARD LAYOUT

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
SCALE:8X



SOLDER MASK DETAILS

4220718/A 09/2016

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0014A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:8X

4220718/A 09/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002

PW0014A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4220202/B 12/2023

NOTES:

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



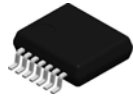
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DB0014A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220762/A 05/2024

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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